

SiPaste® 3.2HF Water-Soluble Solder Paste for Fine Feature SiP Application

- Exceptional printing for small aperture with Type 5, Type 6, and Type 7 powder sizes
- Long stencil life
- Good response-to-pause
- Outstanding slump resistance
- Superior fine-pitch soldering ability

SiPaste® C201HF

Cleanable Solder Paste for Tight-Pitch SiP Application

- Benign, cleanable residue designed for cleaning with semi-aqueous cleaning technology
- Superior cleaning under low-standoff height and fine-pitch components
- Long stencil life
- Outstanding wetting power at fine pitches
- Consistent response to pause performance

Major Users

- Front-end-modules in all leading mobile phones



>2,000,000,000
SiP packages built

Contact our engineers: **Sze Pei Lim or Evan Griffith**
Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.